

BAS316WS-AH

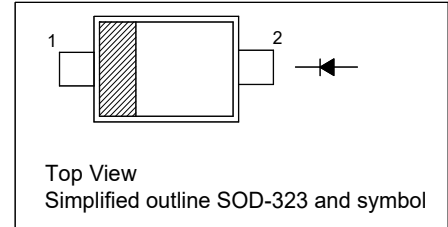
Silicon Epitaxial Planar Switching Diode

Features

- AEC-Q101 Qualified
- High-speed switching
- Halogen and Antimony Free(HAF), RoHS compliant

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



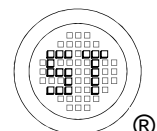
Absolute Maximum Ratings ($T_a = 25\text{ }^\circ\text{C}$)

Parameter	Symbol	Value	Unit
Repetitive Peak Reverse Voltage	V_{RRM}	100	V
Reverse Voltage	V_R	100	V
Continuous Forward Current	I_F	250	mA
Repetitive Peak Forward Current	I_{FRM}	500	mA
Non-Repetitive Peak Forward Current	I_{FSM}	4 1 0.5	A
		$t = 1\ \mu\text{s}$	
		$t = 1\ \text{ms}$	
		$t = 1\ \text{s}$	
Total Power Dissipation	P_{tot}	200	mW
Junction Temperature	T_j	150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	- 65 to + 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Ambient ¹⁾	$R_{\theta JA}$	625	$^\circ\text{C/W}$

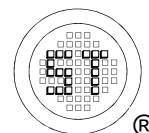
¹⁾ Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



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Characteristics at $T_a = 25\text{ }^\circ\text{C}$

Parameter	Symbol	Min.	Max.	Unit
Reverse Breakdown Voltage at $I_R = 100\text{ }\mu\text{A}$	$V_{(BR)R}$	100	-	V
Forward Voltage at $I_F = 1\text{ mA}$ at $I_F = 10\text{ mA}$ at $I_F = 50\text{ mA}$ at $I_F = 150\text{ mA}$	V_F	- - - -	0.715 0.855 1 1.25	V
Reverse Current at $V_R = 25\text{ V}$ at $V_R = 75\text{ V}$ at $V_R = 25\text{ V}, T_J = 150\text{ }^\circ\text{C}$ at $V_R = 75\text{ V}, T_J = 150\text{ }^\circ\text{C}$	I_R	- - - -	30 1 30 50	nA μA μA μA
Diode Capacitance at $V_R = 0\text{ V}, f = 1\text{ MHz}$	C_{tot}	-	1.5	pF
Reverse Recovery Time at $I_F = 10\text{ mA}, V_R = 6\text{ V}, R_L = 100\text{ }\Omega, I_{rr} = 0.1 \times I_R$	t_{rr}	-	4	ns



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Electrical Characteristics Curves

Fig 1. Power Derating Curve

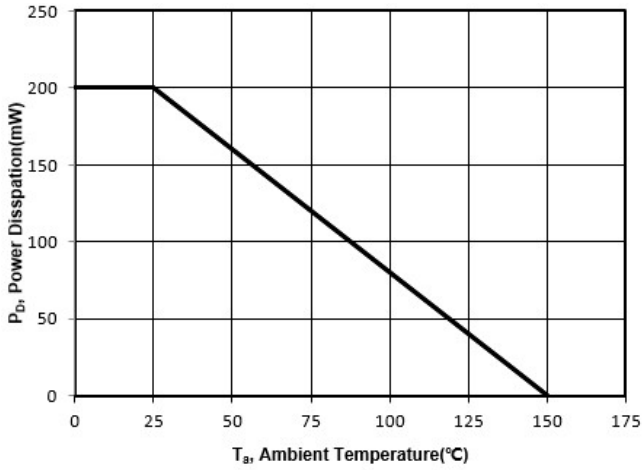


Fig 2. Capacitance Characteristics

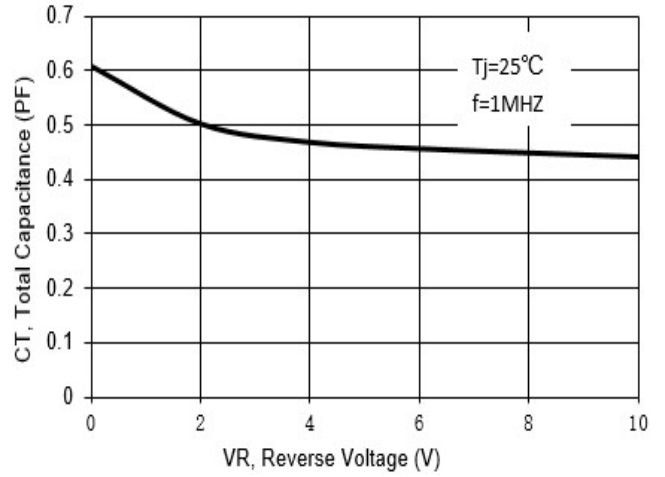


Fig 3. Reverse Characteristics

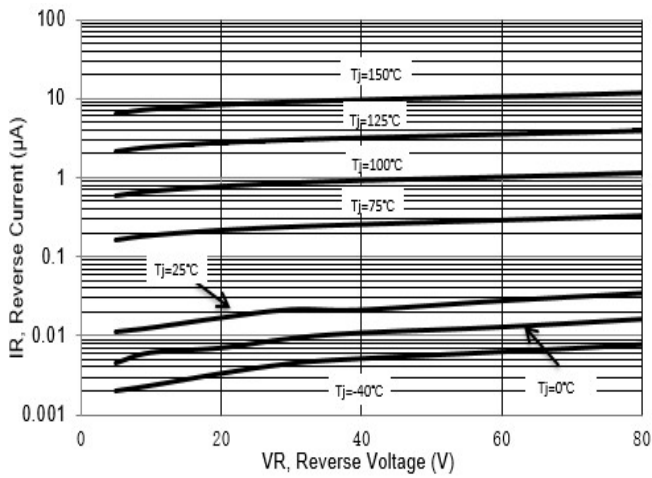
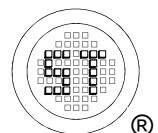
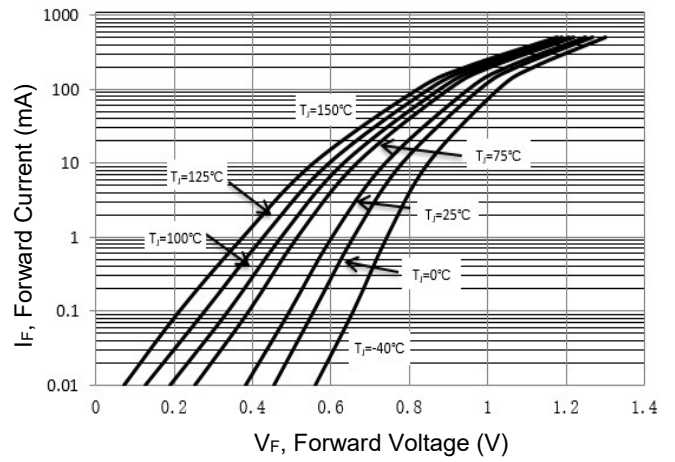


Fig 4. Forward Characteristics

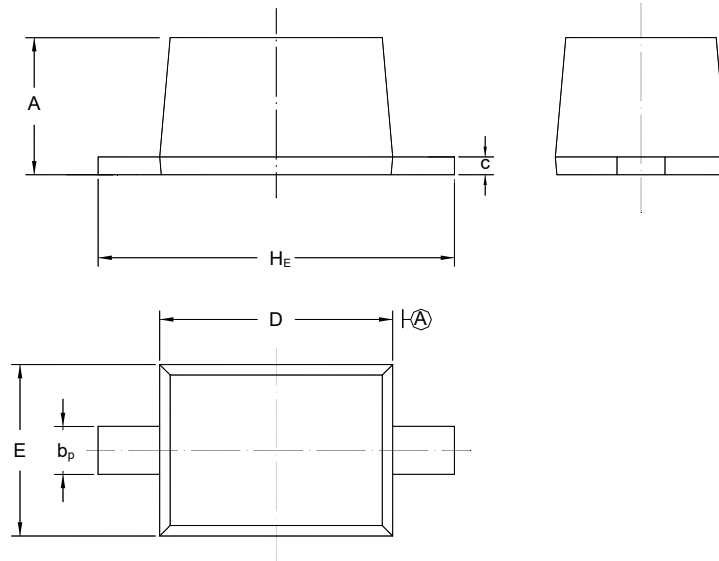


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PACKAGE OUTLINE

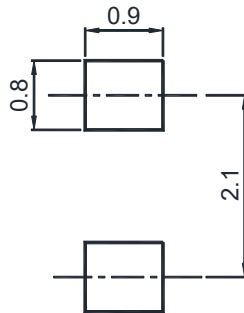
Plastic surface mounted package; 2 leads

SOD-323



UNIT	A	b _p	C	D	E	H _E
mm	1.10 0.80	0.40 0.25	0.15 0.10	1.80 1.60	1.35 1.15	2.80 2.30

Recommended Soldering Footprint



Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
SOD-323	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

Marking information

" W2 " = Part No.
 " III " = Cathode line
 " • " = HAF (Halogen and Antimony Free)
 Font type: Arial

